



YOUSHANG SEMICONDUCTOR

设计研发新型功率器件

各类小信号开关

中低压及高压大电流等场效应管

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企业微信二维码



企业QQ二维码

Product Summary

BV _{DSS}	R _{DS(ON)} Max	I _D Max T _c = +25°C (Note 4)
40V	8.6mΩ @ V _{GS} = 10V	45A

Features and Benefits

- Rated to +175°C – Ideal for High Ambient Temperature Environments
- High Conversion Efficiency
- Low R_{DS(ON)} – Minimizes On-State Losses
- Low Input Capacitance
- Fast Switching Speed

Description and Applications

This MOSFET is designed to minimize the on-state resistance (R_{DS(ON)}) yet maintain superior switching performance, marking it ideal for high-efficiency power-management applications.

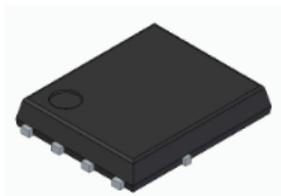
- Backlighting
- Power-management functions
- DC-DC converters

Mechanical Data

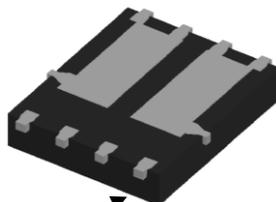
- Package: PowerDI[®]5060-8
- Package Material: Molded Plastic, "Green" Molding Compound. UL Flammability Classification Rating 94V-0
- Moisture Sensitivity: Level 1 per J-STD-020
- Terminals: Finish – Matte Tin Annealed over Copper Leadframe. Solderable per MIL-STD-202, Method 208 
- Weight: 0.097 grams (Approximate)

Site 1:

PowerDI5060-8 (Type C)

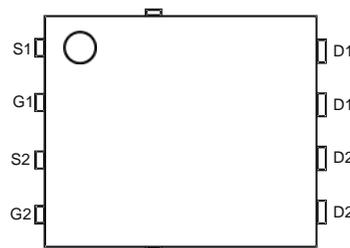
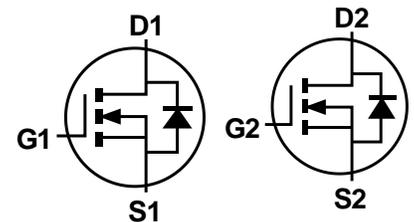


Top View



Pin 1

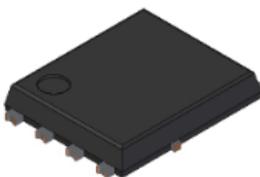
Bottom View


 Pin out
Top View


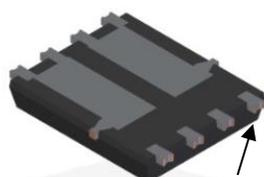
Equivalent Circuit

Site 2:

PowerDI5060-8/SWP (Type UXD)

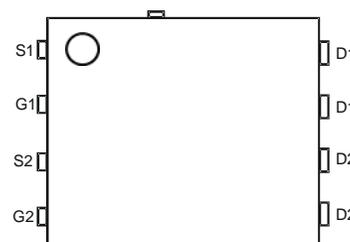
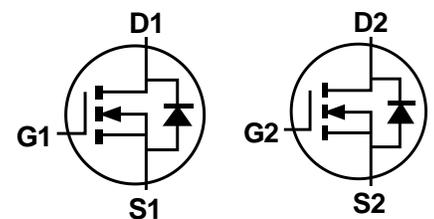


Top View



Pin 1

Bottom View


 Pin out
Top View


Equivalent Circuit

Maximum Ratings (@T_A = +25°C, unless otherwise specified.)

Characteristic		Symbol	Value	Unit
Drain-Source Voltage		V _{DSS}	40	V
Gate-Source Voltage		V _{GSS}	±20	V
Continuous Drain Current (Note 6)	T _C = +25°C (Note 4) T _C = +100°C	I _D	45 38.1	A
Continuous Drain Current (Note 7)	Steady State T _A = +25°C T _A = +100°C	I _D	14.2 11.9	A
Pulsed Drain Current (10μs Pulse, Duty Cycle = 1%)		I _{DM}	90	A
Maximum Continuous Body Diode Forward Current (Note 6)		I _S	34	A
Avalanche Current, L = 0.1mH		I _{AS}	20	A
Avalanche Energy, L = 0.1mH		E _{AS}	89	mJ

Thermal Characteristics

Characteristic		Symbol	Value	Unit
Total Power Dissipation (Note 7)	T _A = +25°C	P _D	2.6	W
Thermal Resistance, Junction to Ambient (Note 7)	Steady State	R _{θJA}	57	°C/W
Total Power Dissipation (Note 6)	T _C = +25°C	P _D	37.5	W
Thermal Resistance, Junction to Case (Note 6)		R _{θJC}	4	°C/W
Operating and Storage Temperature Range		T _J , T _{STG}	-55 to +175	°C

Notes: 6. Thermal resistance from junction to soldering point (on the exposed drain pad).
 7. Device mounted on FR-4 substrate PC board, 2oz. copper, with thermal bias to bottom layer 1inch square copper plate.

Electrical Characteristics (@T_A = +25°C, unless otherwise specified.)

Characteristic	Symbol	Min	Typ	Max	Unit	Test Condition
OFF CHARACTERISTICS (Note 8)						
Drain-Source Breakdown Voltage	BV _{DSS}	40	—	—	V	V _{GS} = 0V, I _D = 1mA
Zero Gate Voltage Drain Current	I _{DSS}	—	—	1	μA	V _{DS} = 32V, V _{GS} = 0V
Gate-Source Leakage	I _{GSS}	—	—	±100	nA	V _{GS} = ±20V, V _{DS} = 0V
ON CHARACTERISTICS (Note 8)						
Gate Threshold Voltage	V _{GS(TH)}	2	—	4	V	V _{DS} = V _{GS} , I _D = 250μA
Static Drain-Source On-Resistance	R _{DS(ON)}	—	7.5	8.6	mΩ	V _{GS} = 10V, I _D = 17A
Diode Forward Voltage	V _{SD}	—	0.85	—	V	V _{GS} = 0V, I _S = 17A
DYNAMIC CHARACTERISTICS (Note 9)						
Input Capacitance	C _{iss}	—	2,026	—	pF	V _{DS} = 30V, V _{GS} = 0V f = 1MHz
Output Capacitance	C _{oss}	—	702	—	pF	
Reverse Transfer Capacitance	C _{rss}	—	84.8	—	pF	V _{DS} = 0V, V _{GS} = 0V, f = 1MHz
Gate Resistance	R _G	—	0.46	—	Ω	
Total Gate Charge	Q _g	—	41.9	—	nC	V _{DS} = 30V, I _D = 20A, V _{GS} = 10V
Gate-Source Charge	Q _{gs}	—	10	—	nC	
Gate-Drain Charge	Q _{gd}	—	11.5	—	nC	
Turn-On Delay Time	t _{D(ON)}	—	7	—	ns	V _{DD} = 30V, V _{GS} = 10V I _D = 20A, R _G = 3Ω
Turn-On Rise Time	t _r	—	11.5	—	ns	
Turn-Off Delay Time	t _{D(OFF)}	—	15.6	—	ns	
Turn-Off Fall Time	t _f	—	8.8	—	ns	
Body Diode Reverse Recovery Time	t _{RR}	—	29.9	—	ns	I _F = 20A, di/dt = 100A/μs
Body Diode Reverse Recovery Charge	Q _{RR}	—	23	—	nC	

Notes: 8. Short duration pulse test used to minimize self-heating effect.
 9. Guaranteed by design. Not subject to product testing.

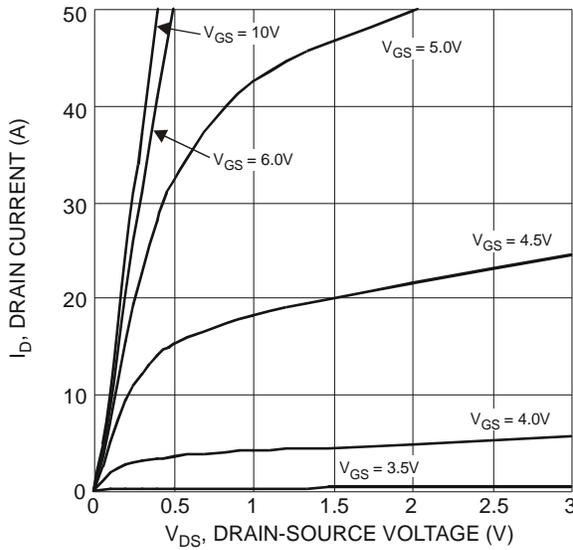


Figure 1 Typical Output Characteristics

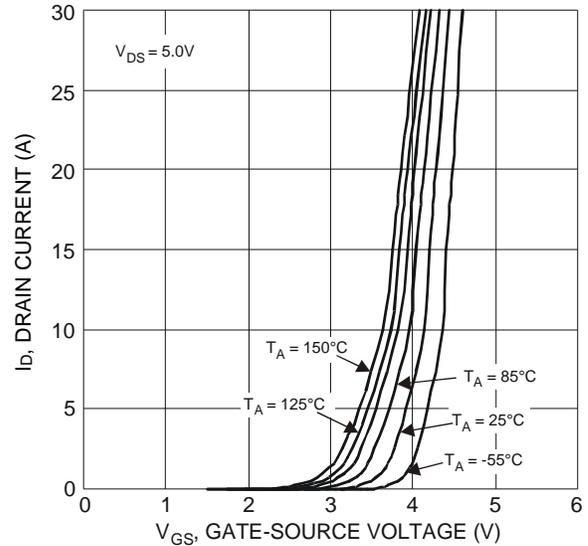


Figure 2 Typical Transfer Characteristics

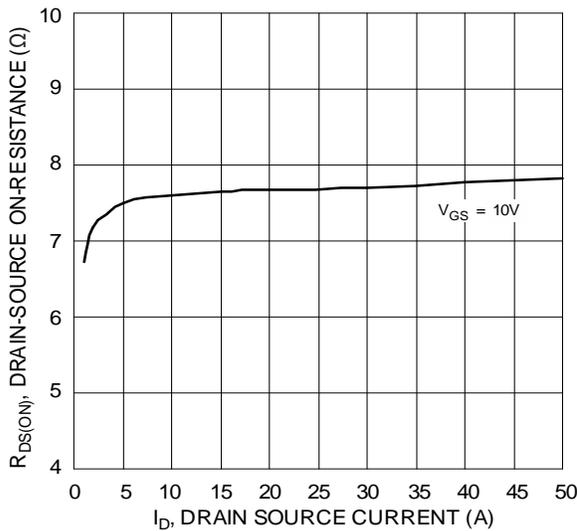


Figure 3 Typical On-Resistance vs. Drain Current and Gate Voltage

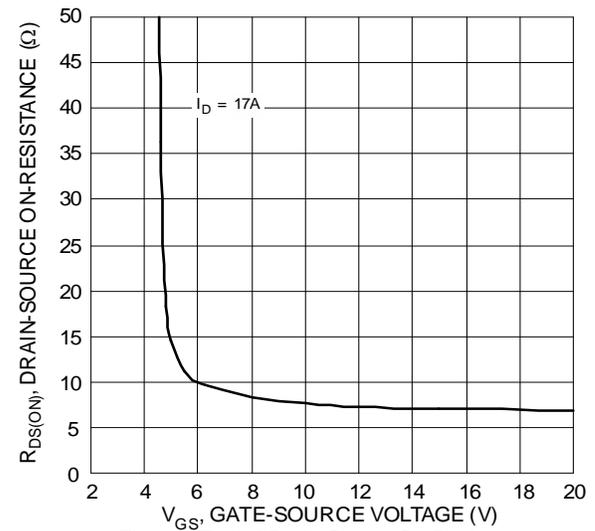


Figure 4 Typical Drain-Source On-Resistance vs. Gate-Source Voltage

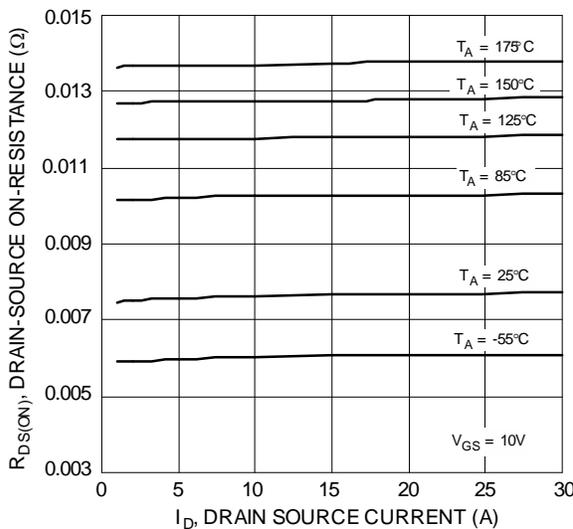


Figure 5 Typical On-Resistance vs. Drain Current and Temperature

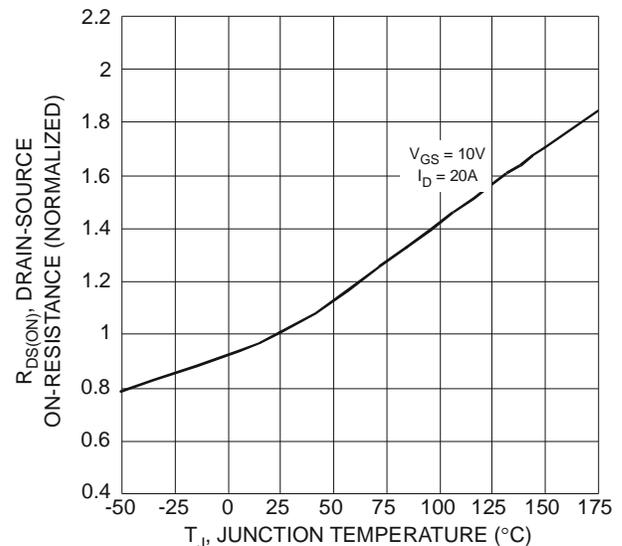


Figure 6 On-Resistance Variation with Temperature

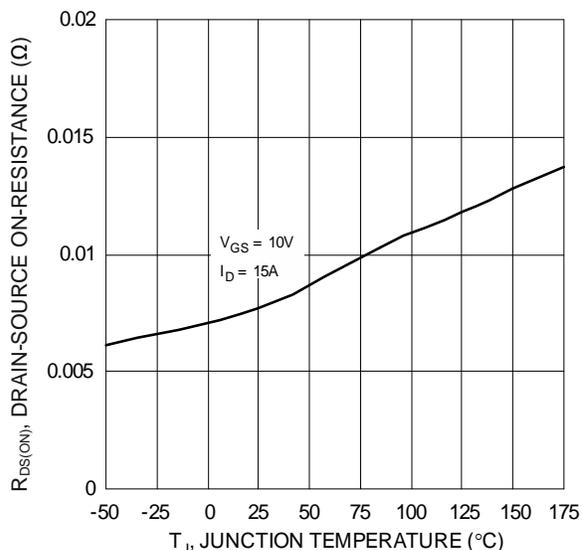


Figure 7 On-Resistance Variation with Temperature

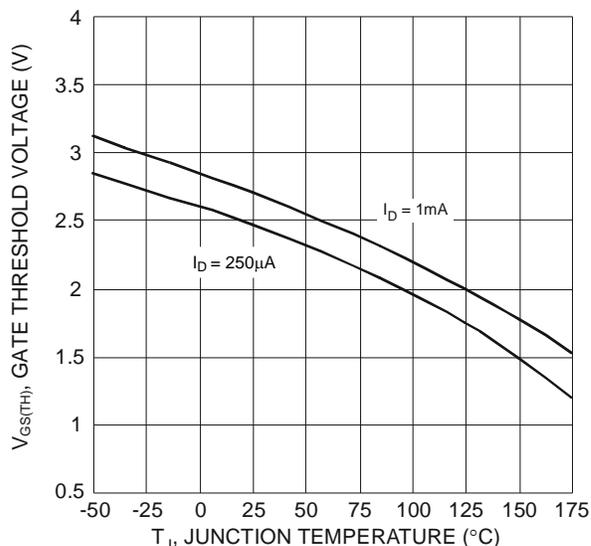


Figure 8 Gate Threshold Variation vs. Junction Temperature

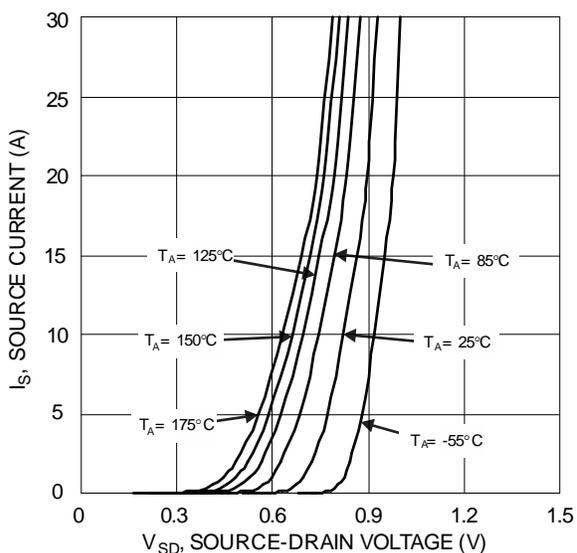


Figure 9 Diode Forward Voltage vs. Current

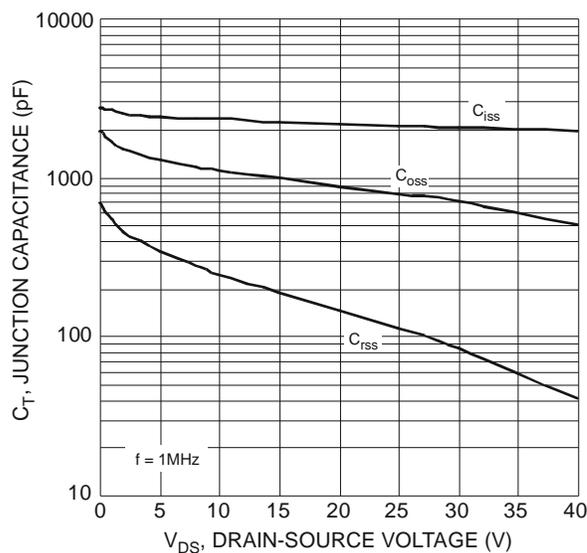


Figure 10 Typical Junction Capacitance

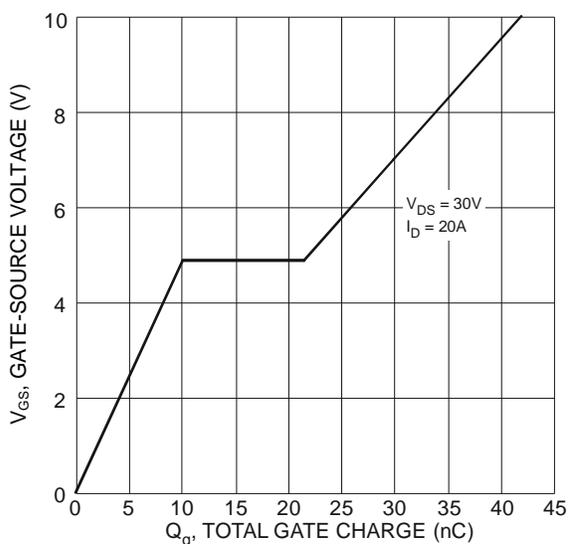


Figure 11 Gate Charge

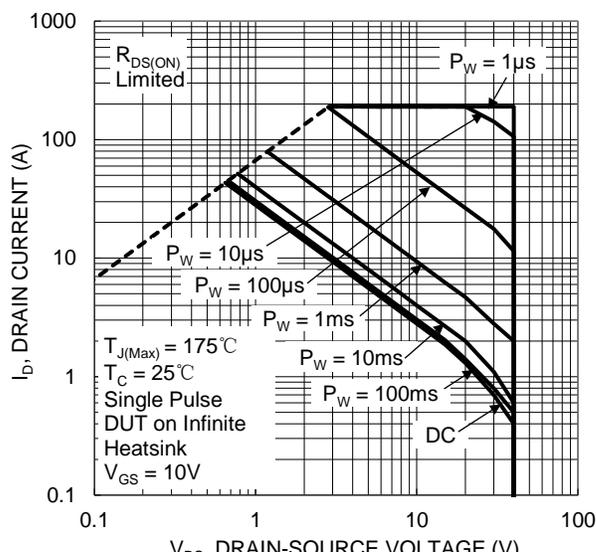
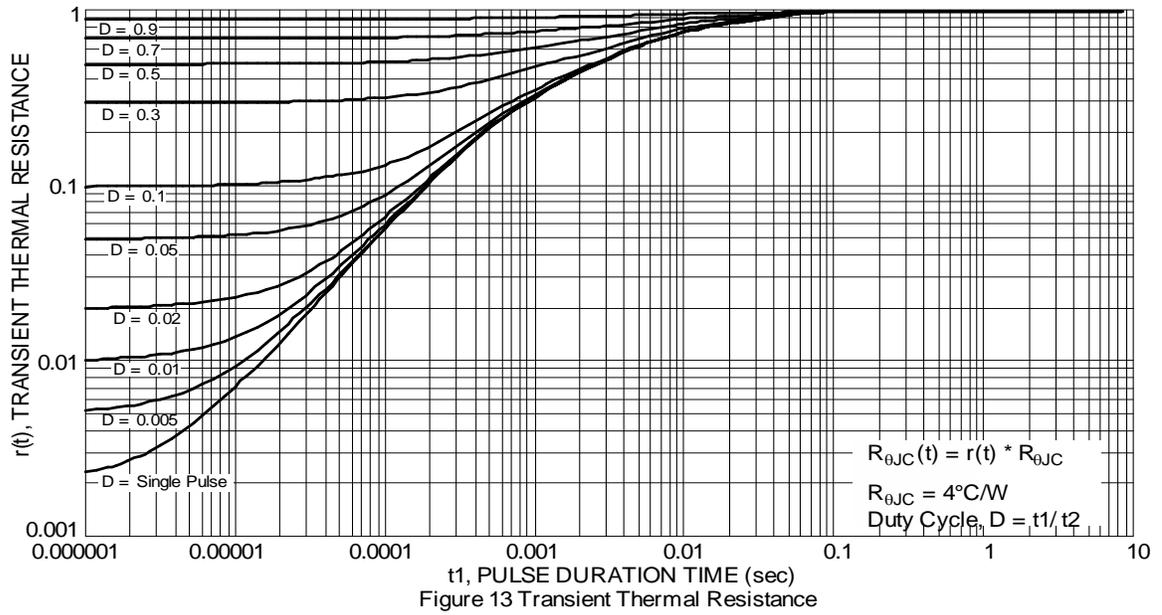


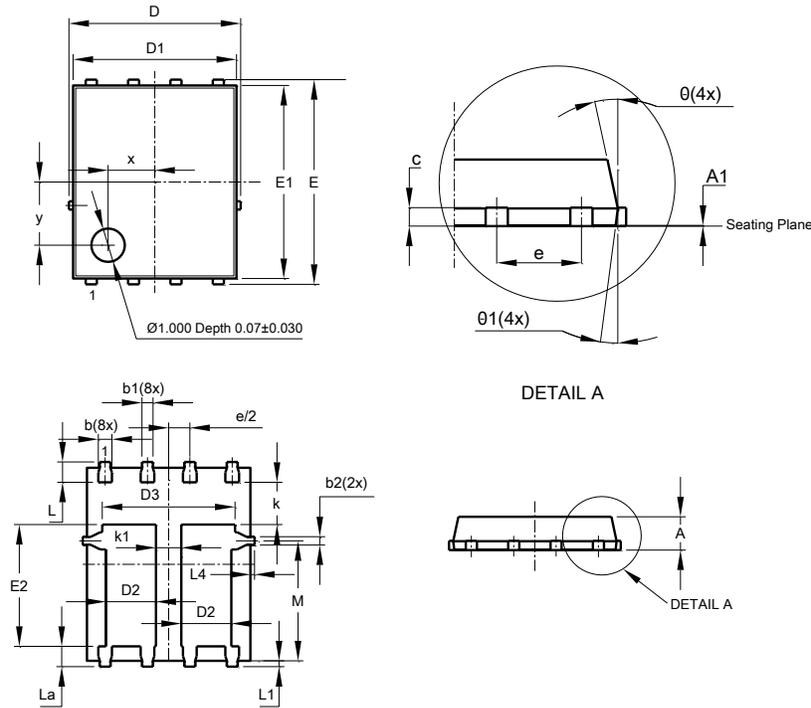
Figure 12 SOA, Safe Operation Area



Package Outline Dimensions

Site 1:

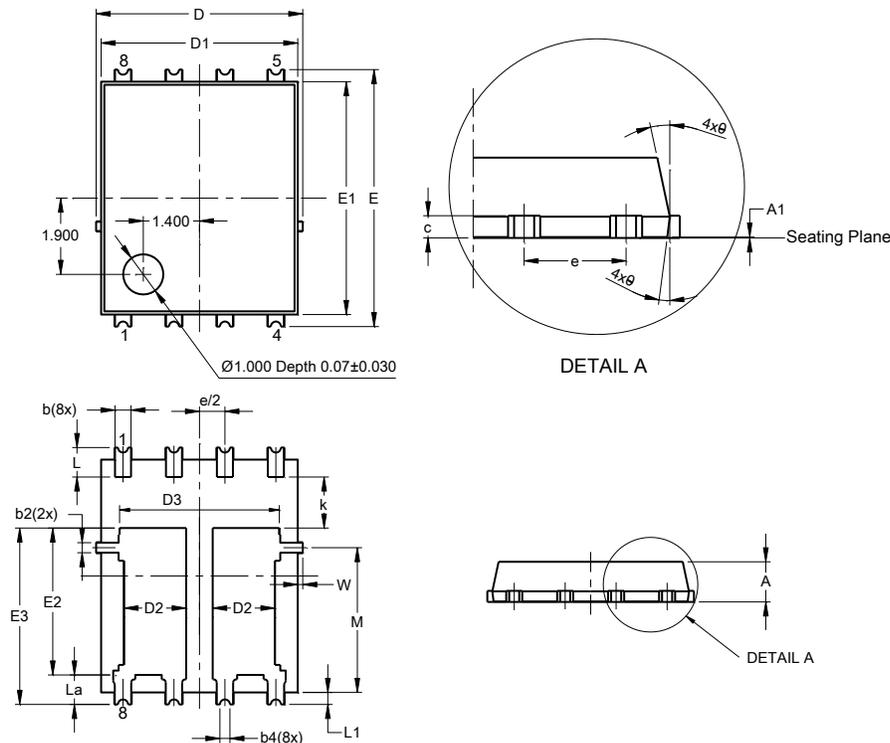
PowerDI5060-8 (Type C)



PowerDI5060-8 (Type C)			
Dim	Min	Max	Typ
A	0.90	1.10	1.00
A1	0	0.05	0.02
b	0.33	0.51	0.41
b1	0.300	0.366	0.333
b2	0.20	0.35	0.25
c	0.23	0.33	0.277
D	5.15 BSC		
D1	4.85	4.95	4.90
D2	1.40	1.60	1.50
D3	-	-	3.98
E	6.15 BSC		
E1	5.75	5.85	5.80
E2	3.56	3.76	3.66
e	1.27BSC		
k	-	-	1.27
k1	0.56	-	-
L	0.51	0.71	0.61
La	0.51	0.71	0.61
L1	0.05	0.20	0.175
L4	-	-	0.125
M	3.50	3.71	3.605
x	-	-	1.400
y	-	-	1.900
θ	10°	12°	11°
θ1	6°	8°	7°
All Dimensions in mm			

Site 2:

PowerDI5060-8/SWP (Type UXD)

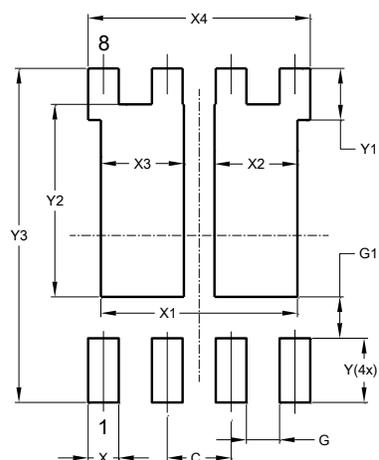


PowerDI5060-8/SWP (Type UXD)			
Dim	Min	Max	Typ
A	0.90	1.10	1.00
A1	0.00	0.05	--
b	0.30	0.50	0.41
b2	0.20	0.35	0.25
b4	0.25REF		
c	0.230	0.330	0.277
D	5.15 BSC		
D1	4.70	5.10	4.90
D2	1.46	1.66	1.55
D3	3.78	4.18	3.98
E	6.40 BSC		
E1	5.60	6.00	5.80
E2	3.46	3.86	3.66
E2a	4.195	4.595	4.395
e	1.27BSC		
k	1.05	--	--
L	0.635	0.835	0.735
La	0.635	0.835	0.735
L1	0.200	0.400	0.300
M	3.205	4.005	3.605
W	0.025	0.225	0.125
θ	10°	12°	11°
θ1	6°	8°	7°
All Dimensions in mm			

Suggested Pad Layout

Site 1:

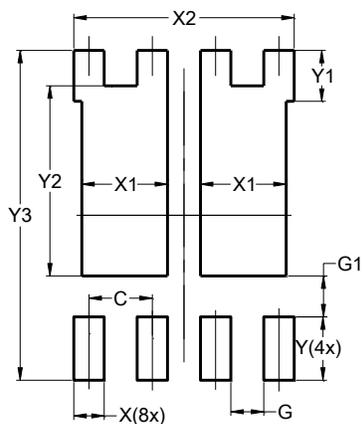
PowerDI5060-8 (Type C)



Dimensions	Value (in mm)
C	1.270
G	0.660
G1	0.820
X	0.610
X1	3.910
X2	1.650
X3	1.650
X4	4.420
Y	1.270
Y1	1.020
Y2	3.810
Y3	6.610

Site 2:

PowerDI5060-8/SWP (Type UXD)



Dimensions	Value (in mm)
C	1.270
G	0.660
G1	0.820
X	0.610
X1	1.720
X2	4.420
Y	1.270
Y1	1.020
Y2	3.810
Y3	6.610